

## IN THE UNITED ENT AND TRADEMARK OFFIĆÉ

Applicants:

T.L. Ritzdorf et al.

Attorney Docket No.: SEMT116049

Application No.: 09/018,783

Group Art Unit:

1763

Filed:

February 4, 1998

Examiner: --

Title:

METHOD FOR FILLING RECESSED MICRO-STRUCTURES WITH

METALLIZATION IN THE PRODUCTION OF A MICROELECTRONIC

**DEVICE** 

## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Seattle, Washington 98101

October 10, 2000

## TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Applicants are aware of the information listed in the attached form that may be materi to the prosecution of the above-identified patent application.

- Copies of the listed patents, publications, and other information are engosed for 1. X the Examiner's use.
- Pursuant to 37 C.F.R. § 1.97(b), this information disclosure statement is being 2. X filed within three months of the filing date of the national application, within three months of the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 in an international application, or before the mailing date of a first Office Action on the merits.
- 3. X The Commissioner is hereby authorized to charge any fees under 37 C.F.R. §§ 1.16, 1.17 and 1.18 which may be required during the entire pendency of the application, or credit any overpayment, to Deposit Account No. 03-1740. This authorization also hereby includes a request for any extensions of time of the

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appropriate length required upon the filing of any reply during the entire prosecution of this application. A copy of this sheet is enclosed.

Respectfully submitted,

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service in a sealed envelope as first class mail with postage thereon fully prepaid and addressed to the Commissioner for Patents, Washington, D.C. 20231, on the below date.

Date: October 10, 2000